

General Description:

Schottky Barrier Diodes make use of the rectification effect of a metal to silicon barrier. They are ideally suited for high frequency rectification in switching regulators & converters. This device offers a low forward voltage performance in a power surface mount package in applications where size and weight are critical.

Features:

- Compact surface mount package with J-bend leads (SMA).
- 1.2 Watt Power Dissipation package.
- 1.0 Ampere, forward voltage less than 600 mV

Ordering:

- 13 inch reel (330 mm); 12 mm Tape; 5,000 units per reel.

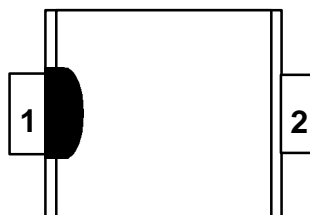
Absolute Maximum Ratings* TA = 25°C unless otherwise noted

Parameter	Value	Units
Storage Temperature	-65 to +150	°C
Maximum Junction Temperature	-65 to +125	°C
Repetitive Peak Reverse Voltage (V_{RRM})	40	V
Average Rectified Forward Current ($T_L = 120^\circ\text{C}$)	1.0	A
Surge Non Repetitive Forward Current (Half wave, single phase, 60 Hz)	30	A
Junction to Case for Thermal Resistance ($R_{\theta JL}$)	9.6	°C/W

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired

**SMA Package
(DO-214AC)**

Top Mark: A140

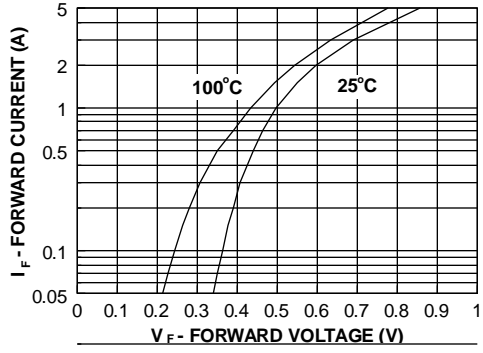


Actual Size

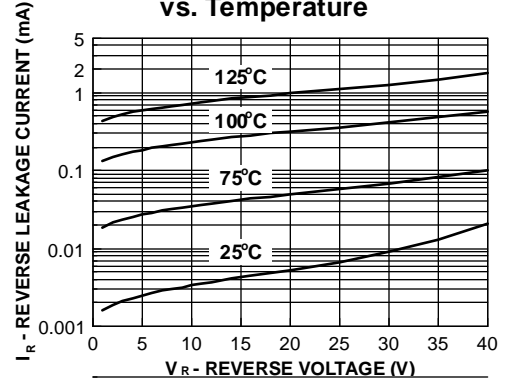
Electrical Characteristics TA = 25°C unless otherwise noted

SYM	CHARACTERISTICS	MIN	MAX	UNITS	TEST CONDITIONS
I_R	Reverse Leakage Current PW 300 us, $\leq 2\%$ Duty Cycle		1.0	mA	$V_R = 40 \text{ V}; T_j = 25^\circ\text{C}$
			10	mA	$V_R = 40 \text{ V}; T_j = 100^\circ\text{C}$
V_F	Forward Voltage PW 300 us, $\leq 2\%$ Duty Cycle		600	mV	$I_F = 1.0 \text{ A}; T_j = 25^\circ\text{C}$

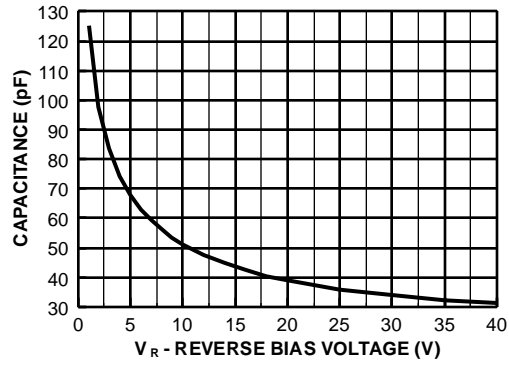
Forward Voltage vs. Temperature



Reverse Leakage Current vs. Temperature



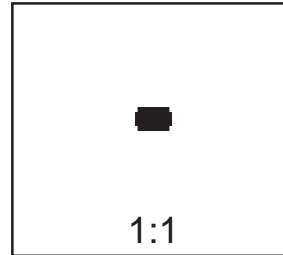
Capacitance vs. Reverse Bias Voltage



SMA/DO-214AC Package Dimensions



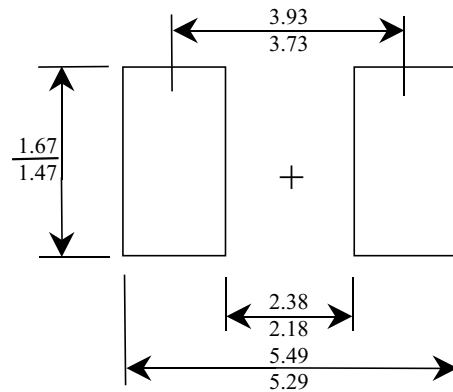
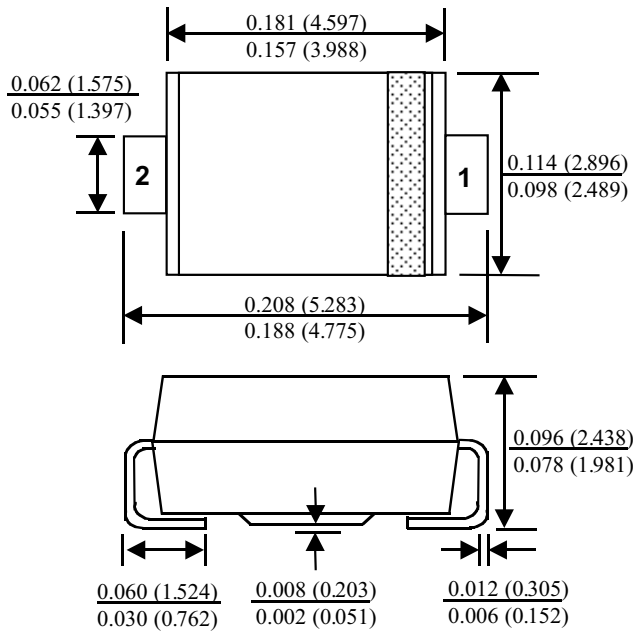
SMA/DO-214AC (FS PKG Code P5)



Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.064



Minimum Recommended
Land Pattern

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx™	HiSeC™	SuperSOT™-8
Bottomless™	ISOPLANAR™	SyncFET™
CoolFET™	MICROWIRE™	TinyLogic™
CROSSVOLT™	POP™	UHC™
E ² CMOS™	PowerTrench®	VCX™
FACT™	QFET™	
FACT Quiet Series™	QS™	
FAST®	Quiet Series™	
FASTr™	SuperSOT™-3	
GTO™	SuperSOT™-6	

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.